

Linear Adjustable Constant Current LED Driver MEL7136A/MEL7136B

General Description

The MEL7136A is a constant current regulator for driving LEDs with low quiescent current and low dropout voltage. The current is adjustable from 10mA to 1A with an external resistor.

The MEL7136B is only a controller, and must be connected to an external NMOS. MEL7136B is an external transistor, is suitable for applications requiring a high output current.

Only one external resistor is required to achieve a constant current LED driver. Soft start, thermal protection and low voltage protection are also provided.

The driver pin EXT is provided for current and voltage extension. Adding an external NMOS or NPN transistor to this pin can extend current and voltage range.

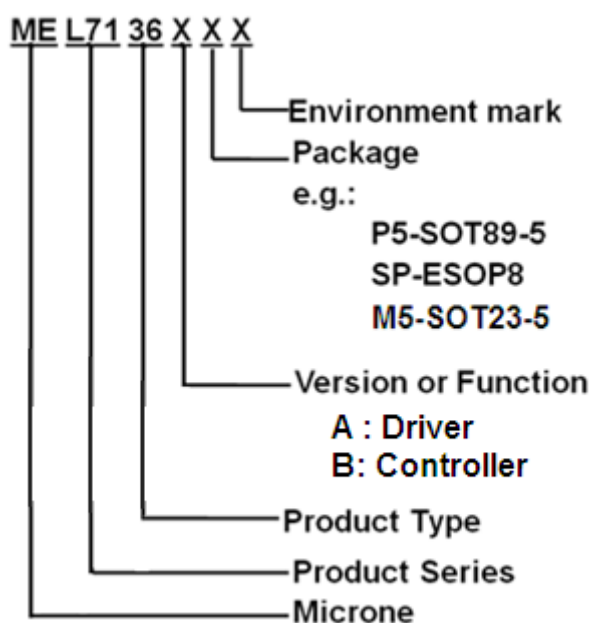
Features

- MEL7136B is only a controller, and must be connected to an external NMOS.
- Sink current: 10mA to 1A adjustable with an external resistor
- Current and voltage range extendable by adding an external NMOS or NPN transistor
- Power supply voltage: 2.7-18V
- Low drop out voltage: 50mV@1A
- Low quiescent current: 80uA
- Thermal Shutdown protection: 165°C
- Soft start
- Low voltage protection: 2.5V
- Package: MEL7136A: SOT89-5, ESOP8
- MEL7136B: SOT23-5

Selection Guide

Typical Application

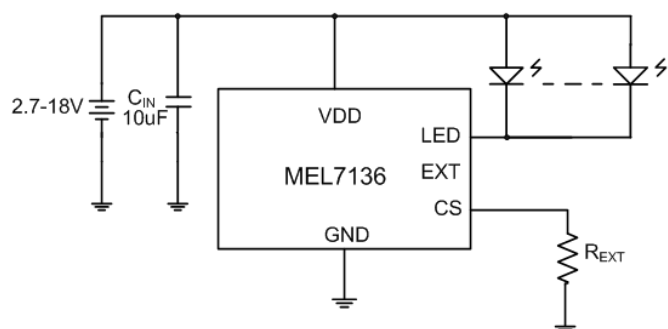
- Power Led driver and controller



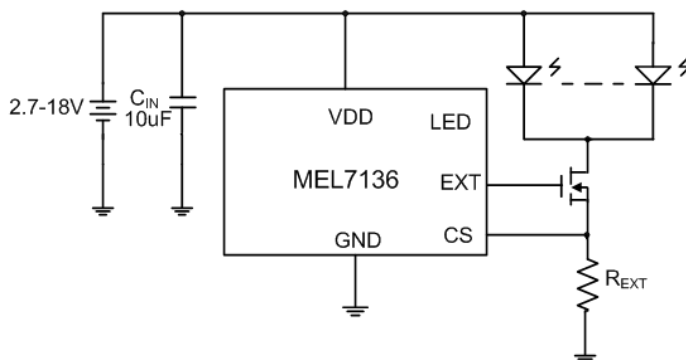
Typical Application Circuit

MEL7136A

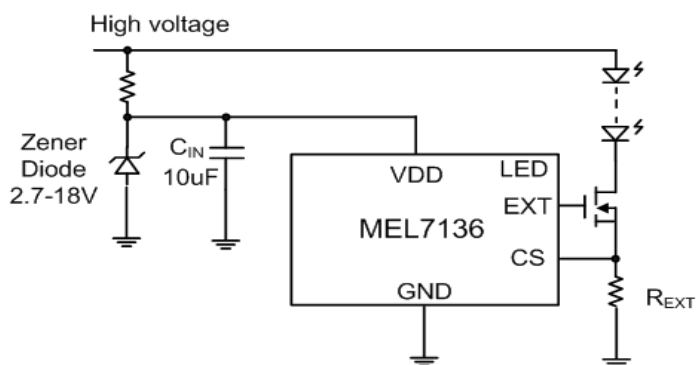
Low Voltage And Light Load (Under 1A)



Low Voltage And Heavy Load (Exceed 1A)

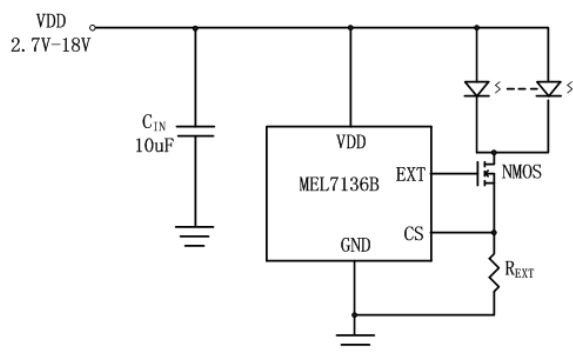


High Voltage Application

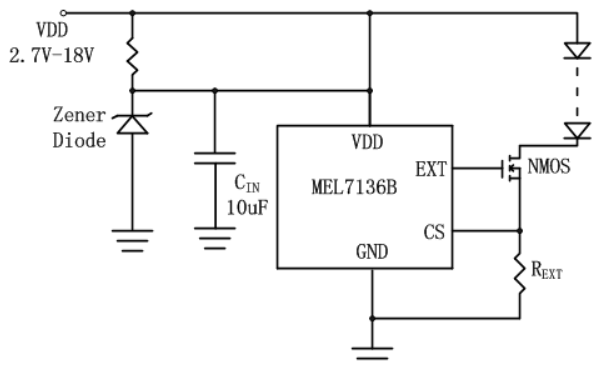


MEL7136B

Low Voltage Application



High Voltage Application

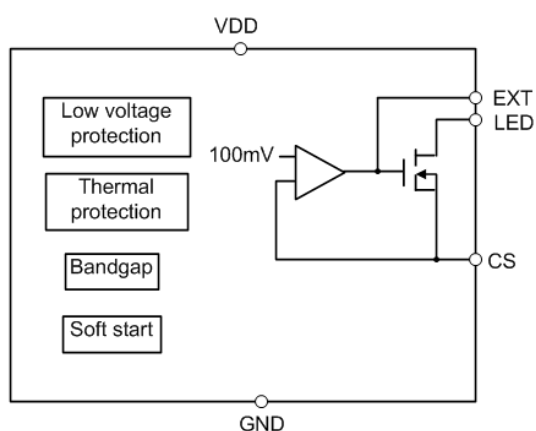


R_{EXT} Resistor Value selection:

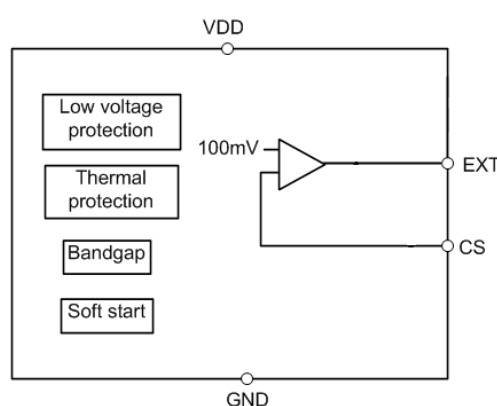
R _{EXT} (Ω)	I _{LED} (mA)
10	10
1	100
0.286	350
0.1	1000

$$I_{LED} = \frac{V_{CS}}{R_{EXT}}$$

Block Diagram

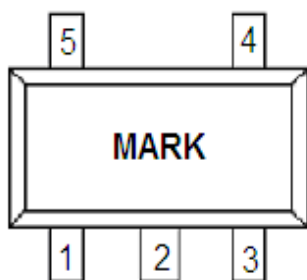


MEL7136A

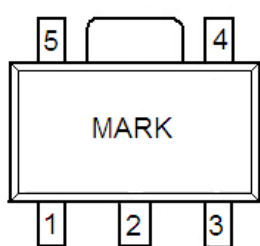


MEL7136B

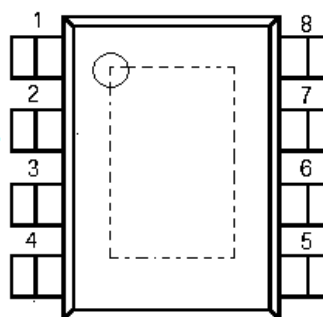
Pin Configuration



SOT23-5(only for MEL7136B)



SOT89-5



ESOP8

Pin Assignment

MEL7136A

Pin Number		Pin Name	Functions
ESOP8	SOT89-5		
2	1	CS	Output current detection
1	2	D(LED)	The negative input feet of LED
3	3	VDD	Power Input
5	4	GND	Ground
7	5	EXT	Driving external NMOS
4,6,8		NC	No connection

MEL7136B

Pin Number		Pin Name	Functions
SOT23-5			
1		NC	NC
2		GND	Ground
3		VDD	Power Input
4		CS	Output current detection
5		EXT	Driving external NMOS

Absolute Maximum Ratings

Parameter	Symbol	Ratings	Units	
Input Voltage	V_{DD}	18	V	
Voltage on LED,CS	V_{LED}, V_{CS}	$-0.3 \sim V_{DD} + 0.3$	V	
Voltage on EXT	V_{EXT}	6	V	
Output Current	I_{OUT}	1.5	A	
Power Dissipation	SOT89-5	P_D	500	mW
			1300 (PCB mounted) ^(*)	
	ESOP8	P_D	2000	mW (T=25°C)
SOT23-5	P_D	300		
Operating Temperature Range	T_{OPR}	$-40 \sim +125$	°C	
Storage Temperature Range	T_{STG}	$-40 \sim +150$	°C	
Lead Temperature		260°C, 4sec		
ESD(ESD voltage for human body model)	V_{ESD}	2000	V	

*1:The power dissipation figure shown in PCB mounted. Please refer to page8-9 for details.

Electrical Characteristics

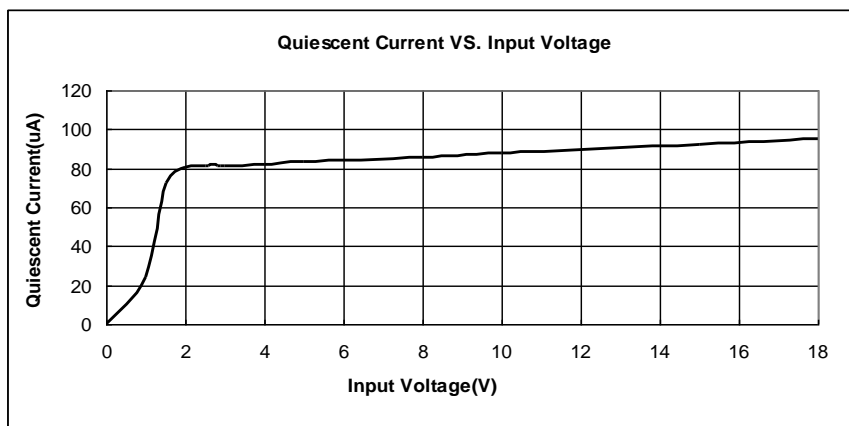
MEL7136A/MEL7136B

($V_{DD}=3.6V$, $T_a=25^{\circ}C$, unless otherwise noted)

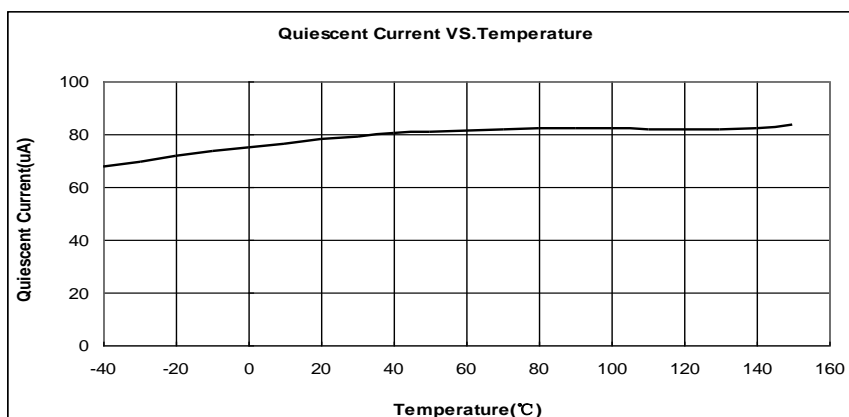
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Sink Current	I_{sink}	$V_{DD}=3.6V$	10		1000	mA
Input Voltage	V_{DD}	$I_{sink}=1A$	2.7		18	V
CS Voltage	V_{CS}		95	100	105	mV
Sink current accuracy	$\Delta I_{LED}/I_{LED}$	$I_{sink}=1A$	-5	-2.5	5	%
Load Regulation	LDR	$V_{LED}=0.2V$ to $3V$ $V_{DD}=3.6V$		0.1	2	mA/V
Line Regulation	LNR	$V_{LED}=3V$ $3.6V \leq V_{DD} \leq 18V$		0.4	2	mA/V
Output dropout voltage	V drop	$V_{DD}=3.6V$, $V_{LED}=0.5V$		50	100	mV
Quiescent Current	I_{SS}	$V_{DD}=3.6V$		80	100	μA
Low Voltage Protection			2.3	2.5	2.7	V
Low voltage hysteresis	V_{hys}			0.15		V
Maximal EXT Voltage	V_{EXT}	$V_{DD}=5.0V$, $V_{CS}=0V$	2.5	3.6	4.5	V
Thermal Shutdown protection	T_{sd}			165		$^{\circ}C$

Type Characteristics

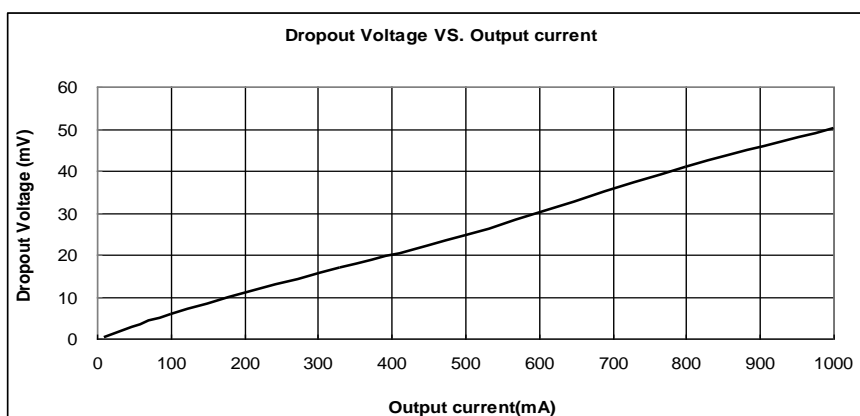
(1) Quiescent Current VS. Input Voltage (No external component)



(2) Quiescent Current VS. Temperature ($V_{DD}=3.6V$)



(3) Dropout Voltage VS. Output current ($V_{DD}=3.6V$)



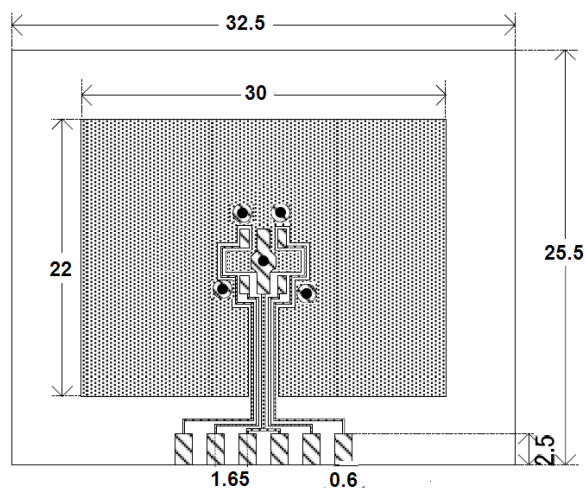
power dissipation

● SOT89-5 power dissipation

The power dissipation data for the SOT89-5 is shown as below. The value of power dissipation varies with the mount board conditions. Please use this data as the reference data taken in the following condions.

1. Measurement condition

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead(pb) free
- Board: Dimensions 30*35mm (1050mm² in one side)
Copper(Cu) traces occupy 50% of the board
Area in top and back faces
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6mm
- Through-hole: 5*0.8 Diameter

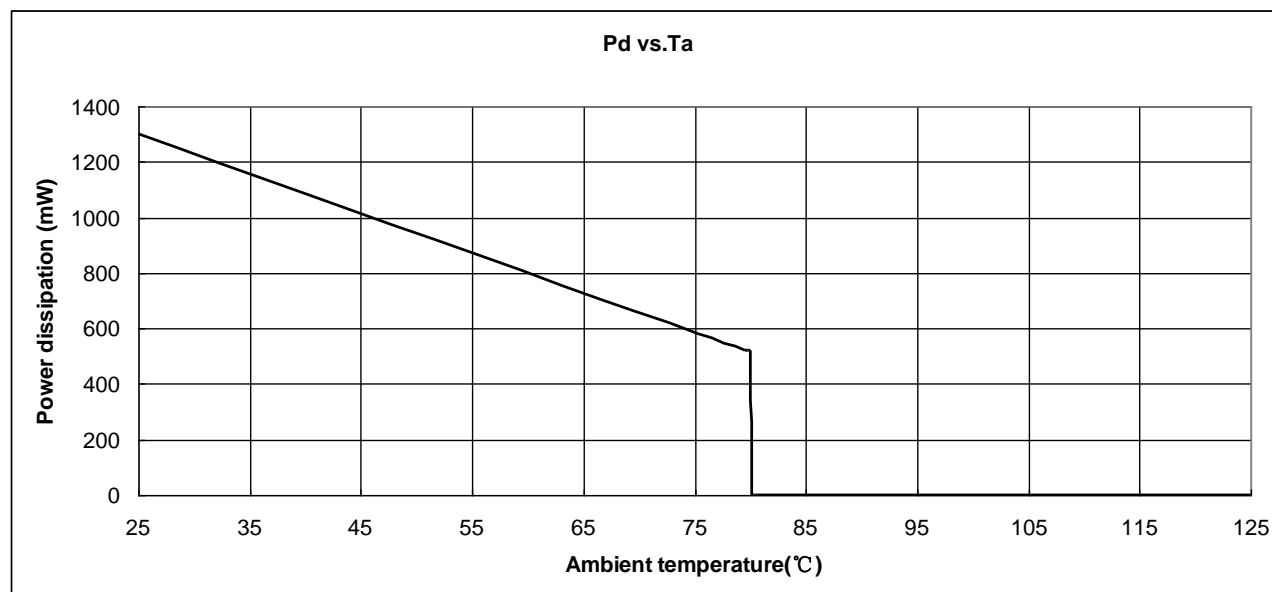


Evaluation Board(Unit:mm)

2. Power dissipation vs. Ambient temperature

Board Mount ($T_j \text{ max}=125 \text{ } ^\circ\text{C}$)

Ambient Temperature($^\circ\text{C}$)	Power Dissipation(mW)	Thermal Resistance($^\circ\text{C}/\text{W}$)
25	1300	76.92
85	520	

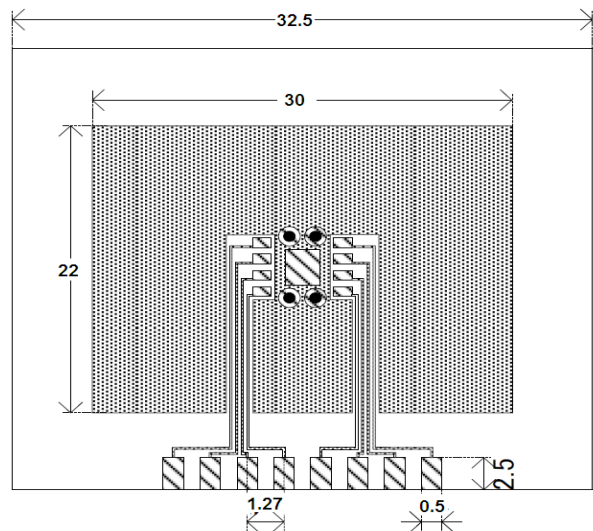


● ESOP8 power dissipation

The power dissipation data for the ESOP8 is shown as below. The value of power dissipation varies with the mount board conditions. Please use this data as the reference data taken in the following condions.

3. Measurement condition

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead(pb) free
- Board: Dimensions 30*35mm (1050mm² in one side)
Copper(Cu) traces occupy 50% of the board
Area in top and back faces
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6mm
- Through-hole: 4*0.8 Diameter

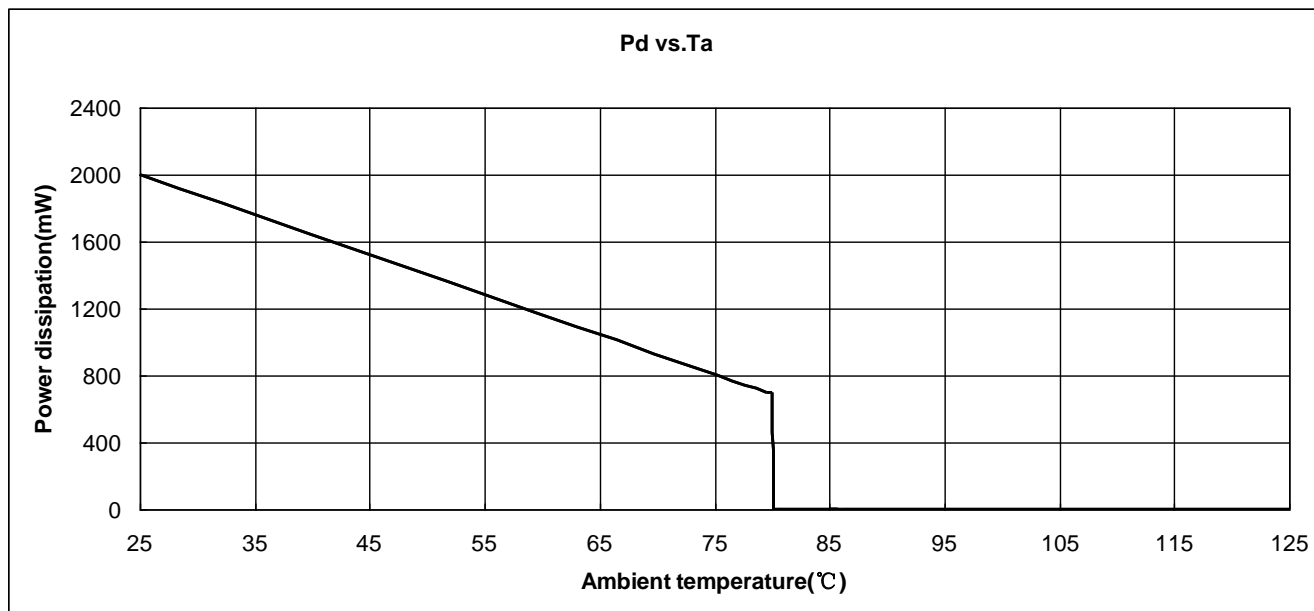


Evaluation Board(Unit:mm)

4. Power dissipation vs. Ambient temperature

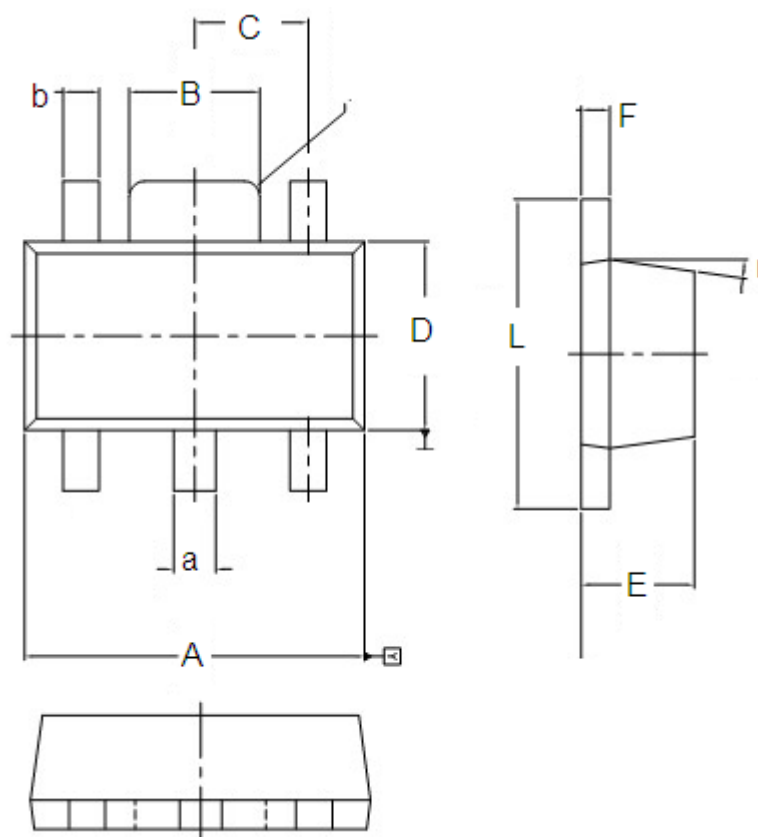
Board Mount ($T_j \text{ max}=125 \text{ }^\circ\text{C}$)

Ambient Temperature($^\circ\text{C}$)	Power Dissipation(mW)	Thermal Resistance($^\circ\text{C}/\text{W}$)
25	2000	66.67
85	700	



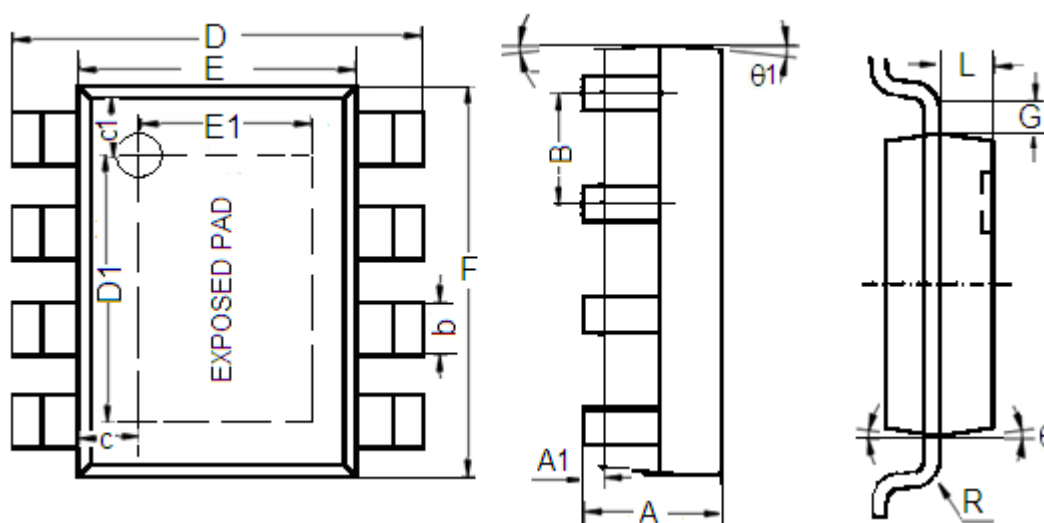
Packaging Information

- Packaging Type: SOT89-5



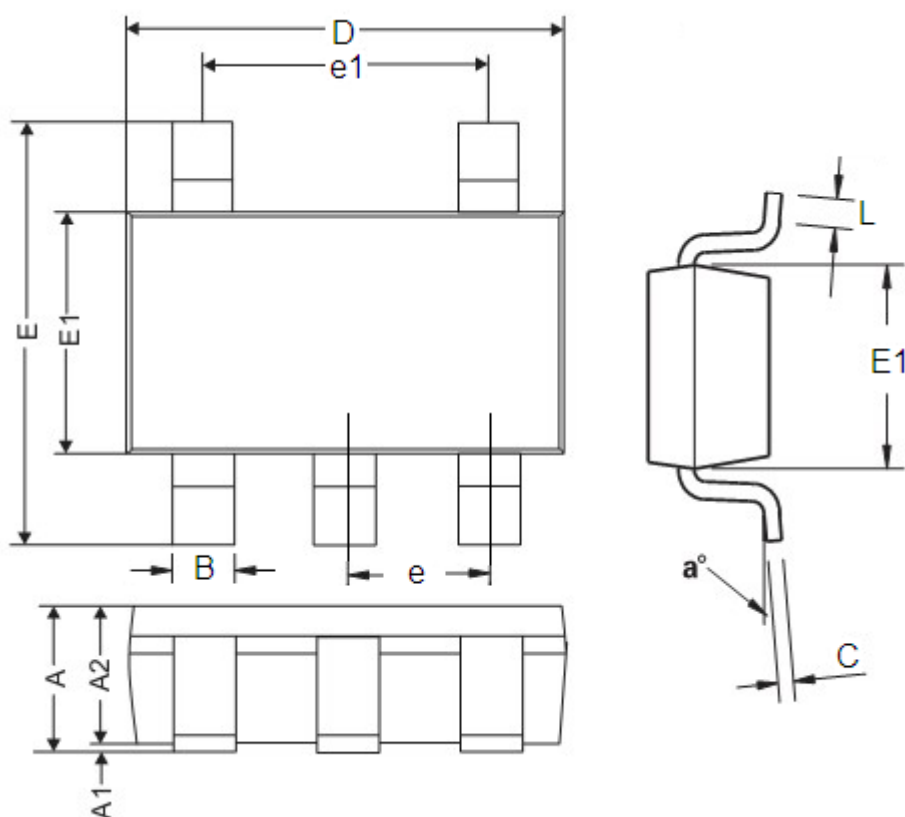
DIM	Millimeters		Inches	
	Min	Max	Min	Max
A	4.4	4.6	0.173	0.181
a	0.5	0.62	0.02	0.024
B	1.63	1.83	0.064	0.072
b	0.44	0.54	0.017	0.021
C	Type:1.5		Type:0.059	
D	2.4	2.6	0.094	0.102
E	1.4	1.6	0.054	0.063
F	0.35	0.43	0.013	0.017
L	3.95	4.25	0.155	0.167
r	Type:8 ⁰		Type:8 ⁰	

● Packaging Type: SOP8-PP



Character	Dimension (mm)		Dimension (Inches)	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.1	0.3	0.004	0.012
B	1.27(Typ.)		0.05(Typ.)	
b	0.330	0.510	0.013	0.020
c	0.9(Typ.)		0.035(Typ.)	
c1	1.0(Typ.)		0.039(Typ.)	
D	5.8	6.2	0.228	0.244
D1	3.202	3.402	0.126	0.134
E	3.800	4.000	0.150	0.157
E1	2.313	2.513	0.091	0.099
F	4.7	5.1	0.185	0.201
L	0.675	0.725	0.027	0.029
G	0.32(Typ.)		0.013(Typ.)	
R	0.15(Typ.)		0.006(Typ.)	
θ1	7°		7°	
θ	8°		8°	

Package type:SOT23-5 Unit:mm(inch)



DIM	Millimeters		Inches	
	Min	Max	Min	Max
A	0.9	1.45	0.0354	0.0570
A1	0	0.15	0	0.0059
A2	0.9	1.3	0.0354	0.0511
B	0.2	0.5	0.0078	0.0196
C	0.09	0.26	0.0035	0.0102
D	2.7	3.10	0.1062	0.1220
E	2.2	3.2	0.0866	0.1181
E1	1.30	1.80	0.0511	0.0708
e	0.95REF		0.0374REF	
e1	1.90REF		0.0748REF	
L	0.10	0.60	0.0039	0.0236
a°	0°	30°	0°	30°

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